

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-16. (Canceled)

17. (Currently Amended) ~~A semiconductor~~ An electronic device comprising:
a printed wiring board;

a first wiring and a second wiring over the printed wiring board;

a first semiconductor element using a crystalline semiconductor film as a first active region and a second semiconductor element using an amorphous semiconductor film as a second active region over an adhesive[[,]];

a third wiring connecting the first semiconductor element and electrically connecting to the first wiring; and

a fourth wiring connecting the second semiconductor element and electrically connecting to the second wiring;

wherein the amorphous semiconductor film is located above the crystalline semiconductor film.

18. (Currently Amended) ~~A semiconductor~~ An electronic device comprising:
a printed wiring board;

a first wiring and a second wiring over the printed wiring board;

a first semiconductor element using a crystalline semiconductor film as a first active region and a second semiconductor element using an amorphous semiconductor film as a second active region over a plastic substrate[[,]];

a third wiring connecting the first semiconductor element and electrically connecting to the first wiring; and

a fourth wiring connecting the second semiconductor element and electrically connecting to the second wiring;

wherein the amorphous semiconductor film is located above the crystalline semiconductor film.

19. (Currently Amended) ~~A semiconductor~~ An electronic device comprising:

a printed wiring board;

a first wiring and a second wiring over the printed wiring board;

a first semiconductor element using a crystalline semiconductor film as a first active region and a second semiconductor element using an amorphous semiconductor film as a second active region over an adhesive[[.]];

a third wiring connecting the first semiconductor element and electrically connecting to the first wiring; and

a fourth wiring connecting the second semiconductor element and electrically connecting to the second wiring;

wherein the first semiconductor element and the second semiconductor element are electrically connected to each other, and

wherein the amorphous semiconductor film is located above the crystalline semiconductor film.

20. (Currently Amended) ~~A semiconductor~~ An electronic device comprising:

a printed wiring board;

a first wiring and a second wiring over the printed wiring board;

a first semiconductor element using a crystalline semiconductor film as a first active region and a second semiconductor element using an amorphous semiconductor film as a second active region over a plastic substrate[[.]];

a third wiring connecting the first semiconductor element and electrically connecting to the first wiring; and

a fourth wiring connecting the second semiconductor element and electrically connecting to the second wiring;

wherein the first semiconductor element and the second semiconductor element are electrically connected to each other, and

wherein the amorphous semiconductor film is located above the crystalline semiconductor film.

21. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 17 or 19, wherein the adhesive is provided with exfoliate paper.

22. (Currently Amended) The ~~semiconductor~~ electronic device according to any one of Claims 17 to 20, wherein the first semiconductor element is a thin film transistor.

23. (Currently Amended) The ~~semiconductor~~ electronic device according to any one of Claims 17 to 20, wherein the second semiconductor element is a diode or a thin film transistor.

24. (Currently Amended) The ~~semiconductor~~ electronic device according to any one of Claims 17 to 20, wherein the semiconductor device includes an optical sensor, a photoelectric conversion element, or a solar battery.

25. (Currently Amended) ~~A semiconductor~~ An electronic device comprising:
a controller over a printed wiring board[.];
a power supply circuit over the printed wiring board[.];
a first wiring and a second wiring over the printed wiring board;
an optical sensor over the printed wiring board comprising a first semiconductor element using a crystalline semiconductor film as a first active region and a second semiconductor element using an amorphous semiconductor film as a second active

region over a plastic substrate;

a third wiring connecting the first semiconductor element and electrically connecting to the first wiring; and

a fourth wiring connecting the second semiconductor element and electrically connecting to the second wiring.

26. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 25, wherein the first semiconductor element is a thin film transistor.

27. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 25, wherein the second semiconductor element is a diode or a thin film transistor.

28. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 25, wherein the semiconductor device is a module of an electronic device.

29. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 25, wherein the semiconductor device ~~provides~~ is provided with a panel having a pixel portion, a scanning line driver circuit, and a signal line driver circuit.

30. (Currently Amended) The ~~semiconductor~~ electronic device according to Claim 25, wherein the optical sensor is provided through an FPC.